Amendments to the Specification:

Please replace the paragraph beginning at page 1, line 26, with the following amended paragraph:

A1

ACFs are usually applied in the manufacture [[off]] of LCD monitors. Sometimes, an ACF is used in connecting the driving chips to the glass substrate of the LCD. Manufacturers refer to this process as COG, i.e., chip on glass. In other cases, an ACF may be applied in connecting the driving chip to a flexible printed circuit (hereinafter referred to as FPC) located on the substrate. This process is referred to as COF.

Please replace the paragraph beginning at page 2, line 4, with the following amended paragraph in which a reference number "5" is added:

A2

Fig.1B shows an application of the ACF. In this case, a substrate 4 is formed with some pads 4a, which are provided for transferring plural signals or energy. On the other side, there is a chip 3 comprised of plural electrodes, wherein the electrodes are respectively formed with a bump 3a. The ACF 5 is provided to connect the chip 3 and the substrate 4.

Please replace the paragraph beginning at page 3, line 13, with the following amended paragraph in which a reference number "6a" is added:

A3

However, as shown in Fig.1H, US5650919 cannot prevent the conductive particles 1 from shifting along the routes indicated by the arrows. In this case, high impedance and short-circuiting are still potential problems. Furthermore, the base 6a of a peak-shape dielectric dam 6 occupies a large space, and may block the bumps in a

A3 cont.

connection. Therefore, the connection must be aligned rather precisely, and insidiously the manufacturing cost will increase.

Please replace the paragraph beginning at page 7, line 6, with the following amended paragraph in which reference numbers "11a" and "11b" are added:

A4

In Fig.2, there is a LCD monitor 100 according to the first embodiment of the present invention. The LCD 100 is comprised of plural circuit devices, which are preferably driving chips 10 (for conciseness, only one is shown). Each of the chips 10 is formed with plural bumps 12 on areas near the two edges 11a, 11b of a base surface 11 thereon. The bumps 12 are made of a kind of metal, such as Au, Cu, Ni, Zn and so on.

Please replace the paragraph beginning at page 7, line 22, with the following amended paragraph in which the reference number "13" is amended to be "15":

A5

The pads 21 include plural first pads 21a and second pads 21b, wherein the first pads 21a are input terminals of the LCD 100, and the second pad 21b are output terminals of the LCD 100.Significantly, in the design of the present invention, there are plural barrier ribs formed on one chip 10. These barrier ribs are formed to separate the conductive particles 31, thereby preventing the improper shifting of the conductive particles 31. The barrier ribs are made from isolating material, such as polyimide (PI). The barrier ribs include plural first barrier ribs 13, second barrier ribs 14, and third barrier ribs 15. In Fig.2, the first barrier ribs 13 extend along a first direction O1,

thereby forming separations between the bumps 12 conducting to the first pads 21a; the second barrier ribs 14 extend along also the first direction O1, thereby forming separations between the bumps 12 conducting to the second pads 21b; and the third barrier ribs [[13]] 15 extend along a second direction O2, thereby separating the bumps 12 conducting to the first pads 21a from that conducting to the second pad 21b.

A5 cont.